

ABSTRACT OF THE DISCLOSURE

A plate assembly on which a wafer is supported in the processing chamber of a processing apparatus facilitates a precise transfer of the wafer therefrom even when a vacuum atmosphere is present in the chamber. The plate assembly includes an underlying support plate and a pad dedicated to support the rear surface of the wafer. A plurality of recesses, in the form of parallel grooves, extend in the upper surface of the pad so that the rear surface of the wafer can also be exposed to the vacuum atmosphere in the processing chamber. Accordingly, a pressure difference at both sides of the wafer is minimized. Thus, the wafer can be raised off of the plate assembly while the precise position thereof is maintained.

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